

单通道ESD保护二极管 UM5059T TDFN2 1.0×0.6

描述

UM5059T ESD保护二极管设计用于取代手机、笔记本电脑和PDA等便携式应用中的MLV。与MLV相比,该器件内置可传导高瞬态电流的大截面积结,具有板级保护的理想电气特性,例如快速响应时间、较低的工作电压、较低的钳位电压和无器件劣化。UM5059T ESD保护二极管可保护敏感的半导体元件免受静电放电 (ESD) 和其他瞬态电压事件的损坏或破坏。UM5059T 采用 TDFN2 1.0×0.6(与SOD923和SOD882兼容)封装,工作电压为5 V。在阵列不实用的应用中,设计人员可以灵活地使用该器件保护单向线路。此外,在电路板空间有限的应用中,该器件可采用分散布置的布局方案。该器件可满足IEC 61000-4-2标准的静电抗扰度要求: ±30kV 空气间隙放电和 ±30kV 接触放电。

应用

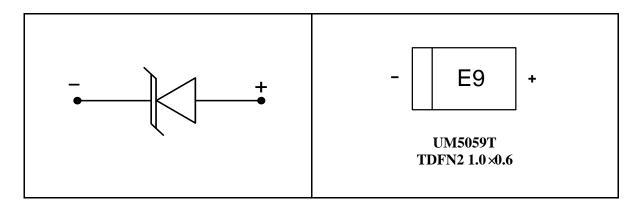
- 手机听筒和配件
- PDA
- 笔记本电脑、台式机和服务器
- 便携式设备
- 无线电话
- 数码相机
- 外围设备
- MP3 播放器

特性

- 数据线瞬态保护,符合IEC 61000-4-2标准: ±30kV(空气间隙放电),±30kV(接触放电)
- 用于便携式电子设备的小型封装
- ESD保护应用中MLV的合适替代品
- 保护一路I/O或电源线
- 低钳位电压
- 反向工作电压: 5V
- 低漏电流
- 固态硅雪崩技术
- 小尺寸外形: 1.0mm × 0.6mm

引脚配置

顶部视图





Ordering Information

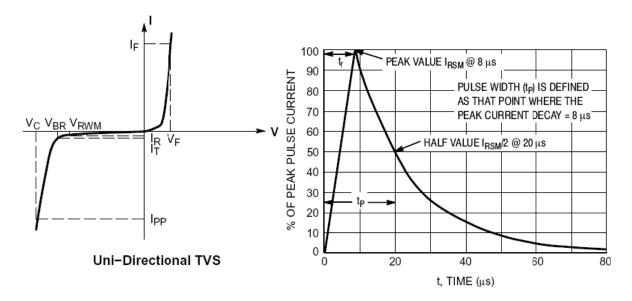
Part Number	Working Voltage	Packaging Type	Channel	Marking Code	Shipping Qty
UM5059T	5.0V	TDFN2 1.0×0.6	1	E9	5000pcs/7 Inch Tape & Reel

Absolute Maximum Ratings

Rating	Symbol	Value	Unit
Peak Pulse Power (t _P =8/20μs)	P_{PK}	140	Watts
Maximum Peak Pulse Current (t _P =8/20μs)	I_{PP}	11	Amps
Lead Soldering Temperature	T_{L}	260 (10 sec.)	${\mathbb C}$
Operating Temperature	T_{J}	-55 to +125	\mathcal{C}
Storage Temperature	T_{STG}	-55 to +150	$\mathcal C$

Symbol Definition

Parameter	Symbol
Maximum Reverse Peak Pulse Current	$ m I_{PP}$
Clamping Voltage @ I _{pp}	V_{C}
Working Peak Reverse Voltage	$ m V_{RWM}$
Maximum Reverse Leakage Current @ V _{RWM}	${ m I}_{ m R}$
Breakdown Voltage @ I _T	$ m V_{BR}$
Test Current	I_{t}
Forward Current	$ m I_F$
Forward Voltage @ I _F	$ m V_F$
Peak Power Dissipation	P_{PK}
Max. Capacitance @ V _R =0V, f=1MHz	C





Electrical Characteristics

(T=25 °C, Device for 5.0V Reverse Stand-off Voltage)

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Reverse Stand-Off Voltage	V_{RWM}				5	V
Reverse Breakdown Voltage	V_{BR}	I _T =1mA	6	6.8	7.8	V
Reverse Leakage Current	I_R	$V_{RWM}=5V$, $T=25$ °C			0.1	μΑ
Clausius Walter	V _C	$I_{PP}=5A, t_P=8/20\mu s$			9.1	17
Clamping Voltage		$I_{PP}=11A, t_P=8/20\mu s$			13	V
Forward Voltage	V_{F}	I _F =10mA		0.8		V
Junction Capacitance	C _J	$V_R=0V$, $f=1MHz$		60	75	pF
Junction Capacitance	C_{J}	$V_R=2.5V$, $f=1MHz$		40	50	pF

Applications Information

Device Connection Options

UM5059T ESD protection diode is designed to protect one data, I/O, or power supply line. The device is unidirectional and may be used on lines where the signal polarity is above ground. The cathode dot should be placed towards the line hat is to be protected.

Circuit Board Layout Recommendations for Suppression of ESD

Good circuit board layout is critical for the suppression of ESD induced transients. The following guidelines are recommended:

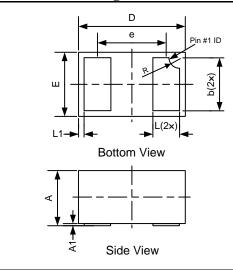
- 1. Place the TVS near the input terminals or connectors to restrict transient coupling.
- 2. Minimize the path length between the TVS and the protected line.
- 3. Minimize all conductive loops including power and ground loops.
- 4. The ESD transient return path to ground should be kept as short as possible.
- 5. Never run critical signals near board edges.
- 6. Use ground planes whenever possible. For multilayer printed-circuit boards, use ground vias.
- 7. Keep parallel signal paths to a minimum.
- 8. Avoid running protection conductors in parallel with unprotected conductor.
- 9. Minimize all printed-circuit board conductive loops including power and ground loops.
- 10. Avoid using shared transient return paths to a common ground point.



Package Information

UM5059T TDFN2 1.0×0.6

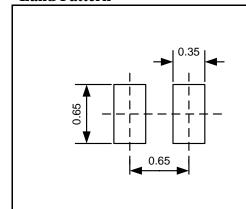
Outline Drawing



DIMENSIONS							
MILLIMETERS			INCHES				
Min	Тур	Max	Min	Тур	Max		
-	-	0.40	-	1	0.016		
0.00	-	0.05	0.000	-	0.002		
0.45	0.50	0.55	0.018	0.020	0.022		
0.95	1.00	1.075	0.037	0.039	0.042		
0.55	0.60	0.675	0.022	0.024	0.027		
0.65TYP			0.026TYP				
0.20	0.25	0.30	0.008	0.010	0.012		
0.00	0.05	0.10	0.000	0.002	0.004		
0.05	0.10	0.15	0.002	0.004	0.006		
	Min - 0.00 0.45 0.95 0.55 0.20 0.00	MILLIME Min Typ - - 0.00 - 0.45 0.50 0.95 1.00 0.55 0.60 0.65TY 0.20 0.00 0.05	MIILIMETERS Min Typ Max - 0.40 0.00 - 0.05 0.45 0.50 0.55 0.95 1.00 1.075 0.55 0.60 0.675 - 0.65TYF 0.20 0.25 0.30 0.00 0.05 0.10	Min Typ Max Min - - 0.40 - 0.00 - 0.05 0.000 0.45 0.50 0.55 0.018 0.95 1.00 1.075 0.037 0.55 0.60 0.675 0.022 0.65TYP 0.20 0.25 0.30 0.008 0.00 0.05 0.10 0.000	Min Typ Max Min Typ - - 0.40 - - 0.00 - 0.05 0.000 - 0.45 0.50 0.55 0.018 0.020 0.95 1.00 1.075 0.037 0.039 0.55 0.60 0.675 0.022 0.024 0.65TYP 0.026TYP 0.008 0.010 0.00 0.05 0.10 0.000 0.002		

Note: R is optional.

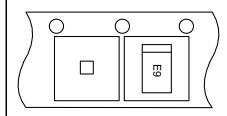
Land Pattern



NOTES:

- 1. Compound dimension: 1.00×0.60:
- 2. Unit: mm;
- 3. General tolerance ± 0.05 mm unless otherwise specified;
- 4. The layout is just for reference.

Tape and Reel Orientation





GREEN COMPLIANCE

Union Semiconductor is committed to environmental excellence in all aspects of its operations including meeting or exceeding regulatory requirements with respect to the use of hazardous substances. Numerous successful programs have been implemented to reduce the use of hazardous substances and/or emissions.

All Union components are compliant with the RoHS directive, which helps to support customers in their compliance with environmental directives. For more green compliance information, please visit:

http://www.union-ic.com/index.aspx?cat_code=RoHSDeclaration

IMPORTANT NOTICE

The information in this document has been carefully reviewed and is believed to be accurate. Nonetheless, this document is subject to change without notice. Union assumes no responsibility for any inaccuracies that may be contained in this document, and makes no commitment to update or to keep current the contained information, or to notify a person or organization of any update. Union reserves the right to make changes, at any time, in order to improve reliability, function or design and to attempt to supply the best product possible.